THE CHINESE UNIVERSITY OF HONG KONG
Office of Admissions and Financial Aid (OAFA)

**HSBC Scholarships and Innovation and Technology Scholarship**

With the generous donations from HSBC, a number of awards under HSBC Greater Bay Area (Hong Kong) Scholarship, HSBC Overseas Scholarship as well as Innovation and Technology Scholarship (IT Scholarship) have been offered to local full-time undergraduate students over the past years.

**Information Session**

If you are interested in these scholarship schemes, do not miss the upcoming information session. Details of the information session are as follows:

- **Date**: 17 November 2022 (Thursday)
- **Time**: 4:30 pm – 5:30 pm
- **Platform**: Zoom

To register for the information session, please complete and submit by 15 November 2022 an online registration form which is obtainable from OAFA website at [http://admission.cuhk.edu.hk](http://admission.cuhk.edu.hk) (Financing Your Studies → Events). The webinar link will be sent to successful registrants by email on or before 15 November 2022.

For enquiries about the Information Session, please contact the Scholarships and Financial Aid Section, OAFA at sfas@cuhk.edu.hk or 3943 7204.

Below is the general information, based on the last exercise, on these three scholarship which will be open for application soon. Details are subject to change.

**HSBC Greater Bay Area (Hong Kong) Scholarship**

Awardees of this Scholarship will receive an award of HK$80,000, and will also be offered learning opportunities (e.g. mentorship and internship) provided by Greater Bay Area-active businesses. To be eligible for this Scholarship, applicants must have a minimum cumulative GPA score of 3.0 or top 15% of class.

**HSBC Overseas Scholarship**

This Scholarship supports the selected candidates to spend a semester or an academic year of their studies as visiting students or exchange students at an overseas university in the next academic year. To be eligible for this Scholarship, applicants must be non-final-year undergraduates who have a minimum cumulative GPA score of 3.7 or top 3% of class (or equivalent). The maximum total value for each scholarship is HK$300,000.

**Innovation and Technology Scholarship**

This Scholarship will financially support non-final-year undergraduates, who are undertaking science-related degrees and preferably with a cumulative GPA of at least 3.3 (or equivalent), to participate in attachment programme(s) overseas and in Mainland China in the next academic year. In addition, the scholarship recipients will be offered an opportunity to join the mentorship programme, service project programme and local internship programme. The maximum amount for each award is HK$150,000.

10 November 2022